

**xLED**

## xLED-NIC-6050 Pin Fin Heat Sink $\Phi$ 60mm for Nichia

### Features VS Benefits

- \* The xLED-NIC-6050 Nichia Pin Fin LED Heat Sinks are specifically designed for luminaires using the Nichia LED engines.
- \* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- \* For spotlight and downlight designs from 900 to 2,200 lumen.
- \* Thermal resistance range  $R_{th}$  3.85°C/W.
- \* Modular design with mounting holes foreseen for direct mounting of Nichia COB series.
- \* Diameter 60.0mm - standard height 50.0mm, Other heights on request.
- \* Forged from highly conductive aluminum.



### Zhaga LED engine and radiator assembly is a unified future international standardization

- \* Below you find an overview of Nichia COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
- \* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.



### Nichia LED Modules directly Mounting Options

Nichia COB LED modules name:

- NFCWL036B;
- NFCLL036B;
- NFCWL060B;
- NFCLL060B;

With the Zhaga Book 3 Holders:

- Ideal Holder:50-2100NC;
- TE LED Holder:2213382-2;

Direct mounting with machine screws M3x6.5mm, Green indicator marks.

With the LEDiL products:

- Lena series: CN14xxx; C13xxx; C12xxx;
- Ronda series: FN15xxx-xx;

Nichia COB LED modules name:

- NVCWL024Z;
- NVCLL024Z;
- NVNW S007Z;
- NJCWS024Z;

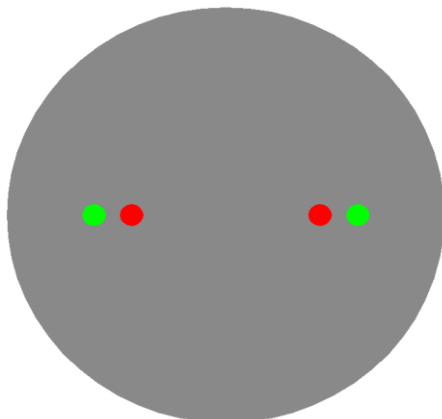
With the Zhaga Book 11 Holders:

- BJB holder:47.319.6180.50;
- TE LED Holder:2213118-1;

Direct mounting with machine screws M3x8mm, Red indicator marks.

With the LEDiL products:

- Lena series: CN14xxx; C13xxx; C12xxx;
- Ronda series: FN15xxx-xx;



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Mounting Options and Drawings & Dimensions

Example: xLED-NIC-6050-B-1,2

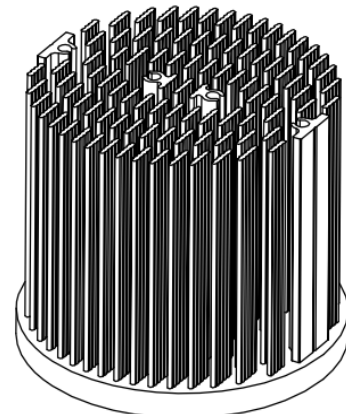
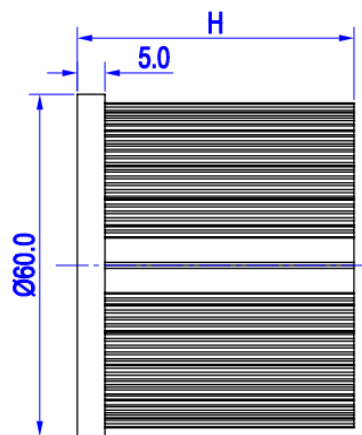
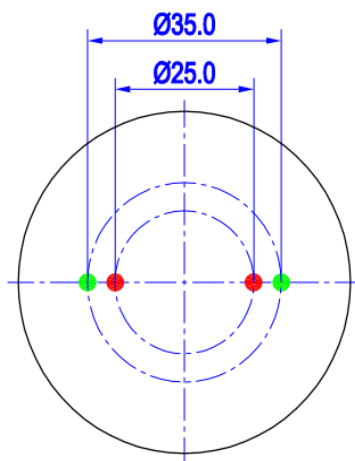
Example: xLED-NIC-60 **1** - **2** - **3**

- 1** Height (mm)
- 2** Anodising Color
  - B-Black
  - C-Clear
  - Z-Custom
- 3** Mounting Options - see graphics for details Combinations available  
Ex.order code - 12  
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.


MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
			Lena series	Ronda series			
N	/	None	None	None	None	None	None
1	NVCWL024Z; NVCLL024Z; NVNWS007Z; NJCWS024Z;	BJB Holder 47.319.6180.50	CN14xxx; C13xxx; C12xxx;	FN15xxx-xx	M3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		TE Holder 22131 18-1					
2	NFCWL036B; NFCLL036B; NFCWL060B; NFCLL060B;	Ideal Holder 50-2100NC					
		TE Holder 2213382-2					



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### xLED-NIC-6050 Pin Fin Heat Sink $\Phi 60\text{mm}$ for Nichia

#### The product data table

	Model No.	xLED-NIC-6050
	Heatsink Size	$\Phi 60 \times H 50\text{mm}$
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	112.0
	Dissipated power (T <sub>hs-amb</sub> , 50°C)	13.0 (W)
	Cooling surface area (mm <sup>2</sup> )	68473
	Thermal Resistance (R <sub>hs-amb</sub> )	3.85 (°C/W)

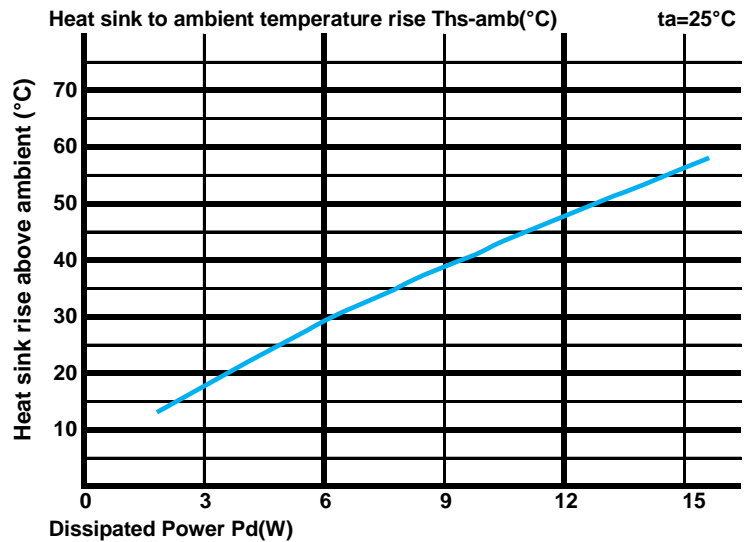
#### The thermal data table

\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

\* To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$ .

Pd - Dissipated power ; Pe - Electrical power ;  $\eta_L$  = Light efficiency of the LED module;

Dissipated Power Pd(W)	Pd = Pe x (1- $\eta_L$ )	Heat sink to ambient thermal resistance R <sub>hs-amb</sub> (°C/W)	Heat sink to ambient temperature rise T <sub>hs-amb</sub> (°C)
		xLED-NIC-6050	
3.0		5.67	17.0
6.0		4.83	29.0
9.0		4.22	38.0
12.0		4.00	48.0
15.0		3.73	56.0



\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [°C/W]; T<sub>hs</sub> - Heatsink temperature; T<sub>a</sub> - Ambient temperature;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is R<sub>junction-case</sub>, the thermal resistance of the TIM outside the package is R<sub>interface (TIM)</sub> [°C/W], the thermal resistance with the heat sink is R<sub>heatsink-ambient</sub> [°C/W], and the ambient temperature is T<sub>ambient</sub> [°C].

\*Thermal resistances outside the package R<sub>interface (TIM)</sub> and R<sub>heatsink-ambient</sub> can be integrated into the thermal resistance R<sub>case-ambient</sub> at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$